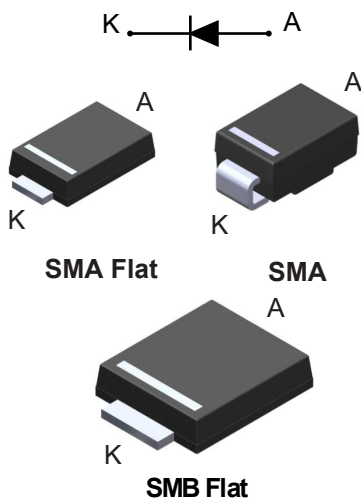


30 V power Schottky rectifier



Features

- Low forward voltage drop for less power dissipation
- Optimized conduction/reverse losses trade-off which lead to the highest efficiency in the applications
- Surface mount miniature package
- Avalanche rated
- ECOPACK®2 component

Applications

- Cordless appliance
- SSD
- Battery charger
- Telecom power
- DC / DC converter

Description

Single chip Schottky rectifiers designed for high frequency miniature switched mode power supplies such as adaptors and on board DC/DC converters.

Packaged in SMA, SMA Flat and SMB Flat, the **STPS2L30** is ideal for use in parallel with MOSFETs in synchronous rectification.

Product status	
STPS2L30	
Product summary	
Symbol	Value
$I_{F(AV)}$	2 A
V_{RRM}	30 V
$T_{j(max.)}$	150 °C
$V_{F(typ.)}$	0.325 V

1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter	Value	Unit
V _{RRM}	Repetitive peak reverse voltage	30	V
I _{F(AV)}	Average forward current, $\delta = 0.5$, square wave	SMA T _L = 120 °C	2 A
		SMA Flat T _L = 130 °C	
		SMB Flat T _L = 135 °C	
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	75 A
P _{ARM}	Repetitive peak avalanche power	t _p = 10 μ s, T _j = 125 °C	108 W
T _{stg}	Storage temperature range	-65 to +150	°C
T _j	Maximum operating junction temperature ⁽¹⁾	+150	°C

1. $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameter

Symbol	Parameter	Max. value	Unit
R _{th(j-l)}	Junction to lead	SMA	°C/W
		SMA Flat	
		SMB Flat	

For more information, please refer to the following application note :

- AN5088 : Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	-		200	μ A
		T _j = 100 °C	-	6	15	mA
V _F ⁽¹⁾	Forward voltage drop	T _j = 25 °C	-		0.45	V
		T _j = 125 °C	-	0.325	0.375	
		T _j = 25 °C	-		0.53	
		T _j = 125 °C	-	0.43	0.51	

1. Pulse test: t_p = 380 μ s, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 0.24 \times I_{F(AV)} + 0.068 \times I_{F(RMS)}^2$$

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

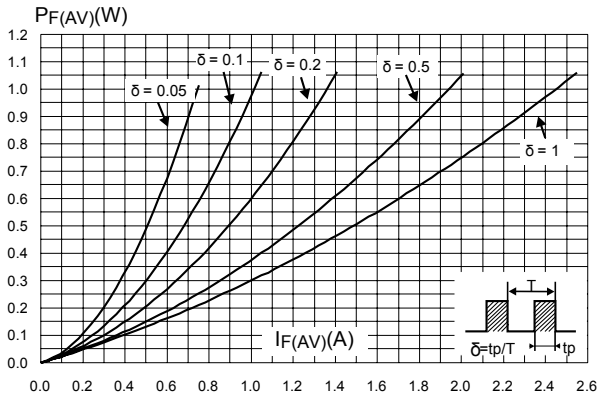
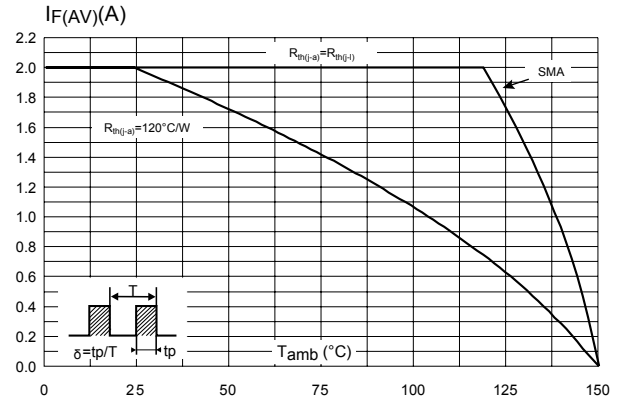
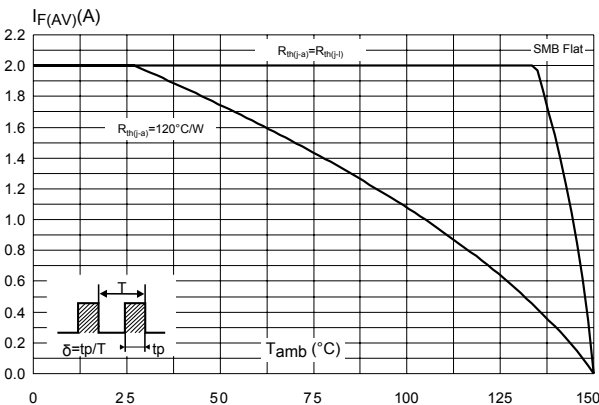
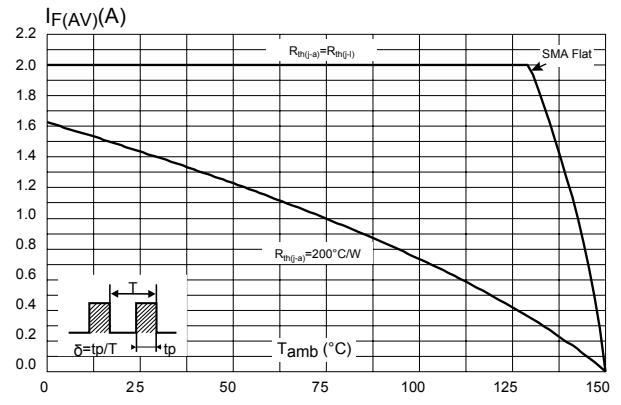
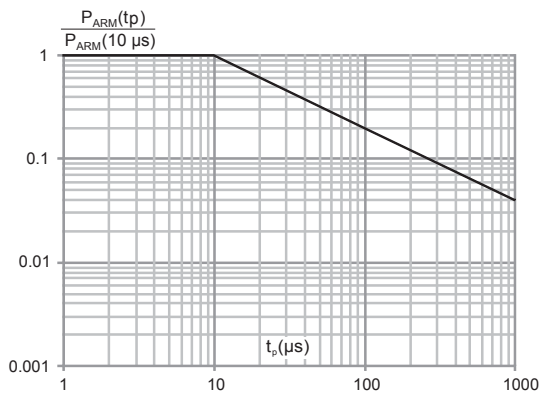
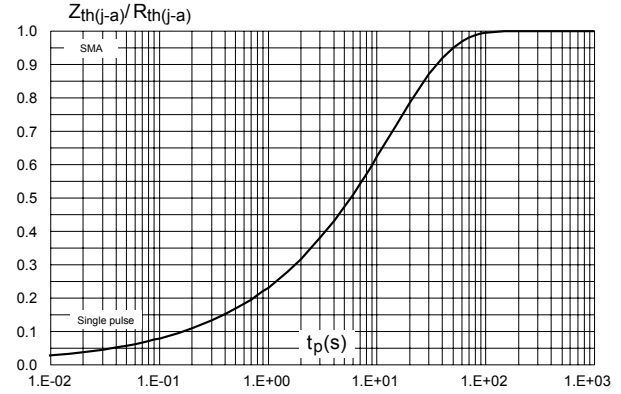
1.1 Characteristics (curves)
Figure 1. Average forward power dissipation versus average forward current

Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$) SMA

Figure 3. Average forward current versus ambient temperature ($\delta = 0.5$, SMB Flat)

Figure 4. Average forward current versus ambient temperature ($\delta = 0.5$, SMA Flat)

Figure 5. Normalized avalanche power derating versus pulse duration ($T_j = 125$ °C)

Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA)


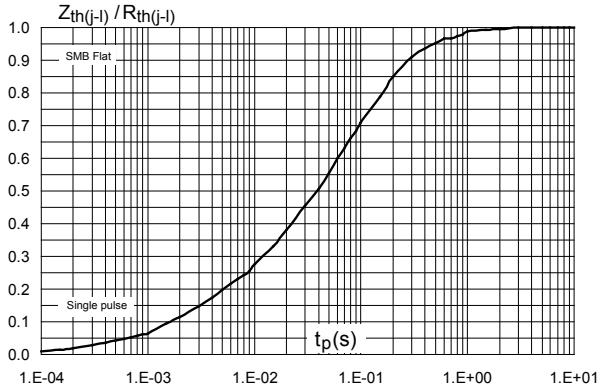
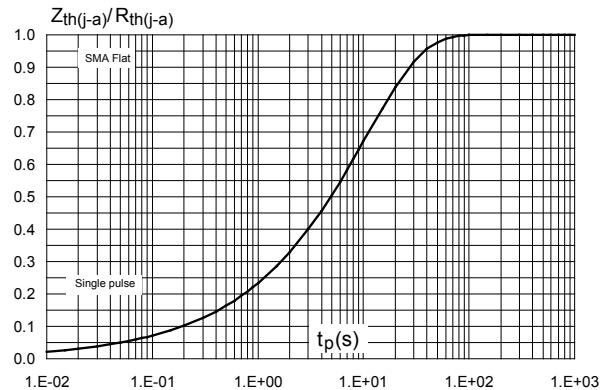
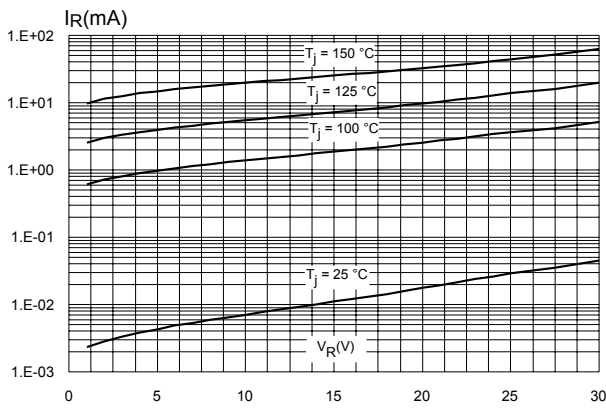
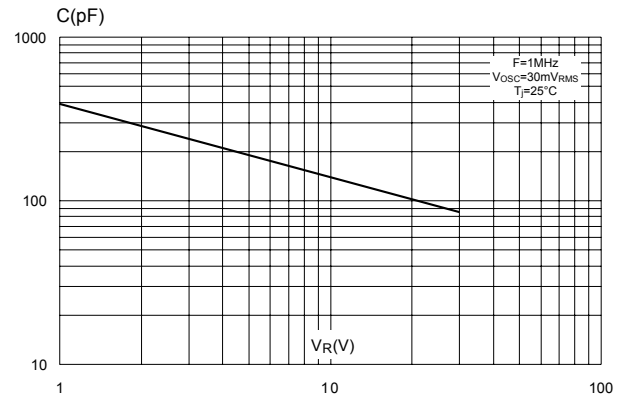
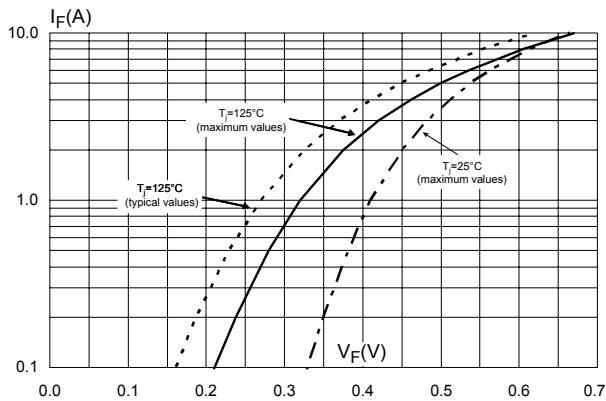
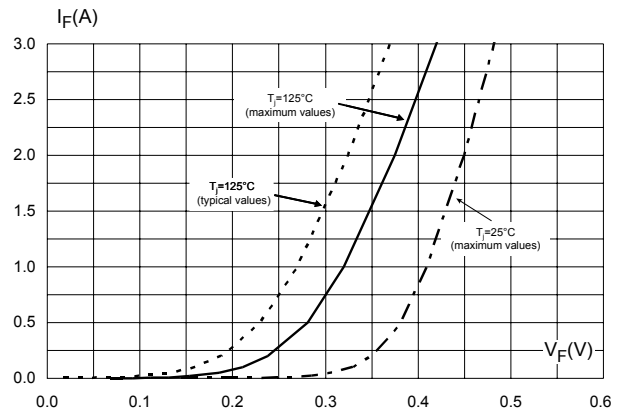
Figure 7. Relative variation of thermal impedance junction to lead versus pulse duration (SMB Flat)

Figure 8. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA Flat)

Figure 9. Reverse leakage current versus reverse voltage applied (typical values)

Figure 10. Junction capacitance versus reverse voltage applied (maximum values)

Figure 11. Forward voltage drop versus forward current (high level)

Figure 12. Forward voltage drop versus forward current (low level)


Figure 13. Thermal resistance junction to ambient versus copper surface under each lead (SMA)

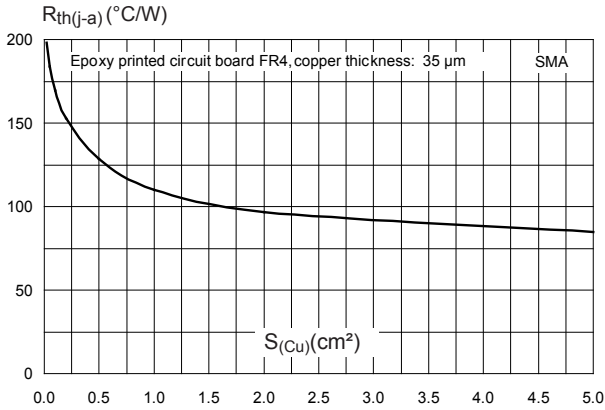


Figure 14. Thermal resistance junction to ambient versus copper surface under each lead (SMB Flat)

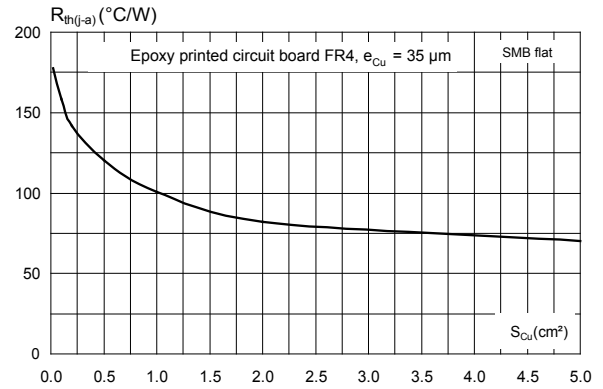
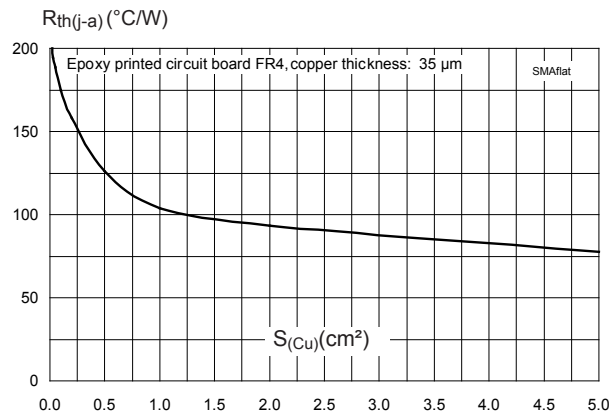


Figure 15. Thermal resistance junction to ambient versus copper surface under each lead (SMA Flat)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK®** packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 SMA package information

- Epoxy meets UL94, V0
- Cooling method : by conduction (C)

Figure 16. SMA package outline

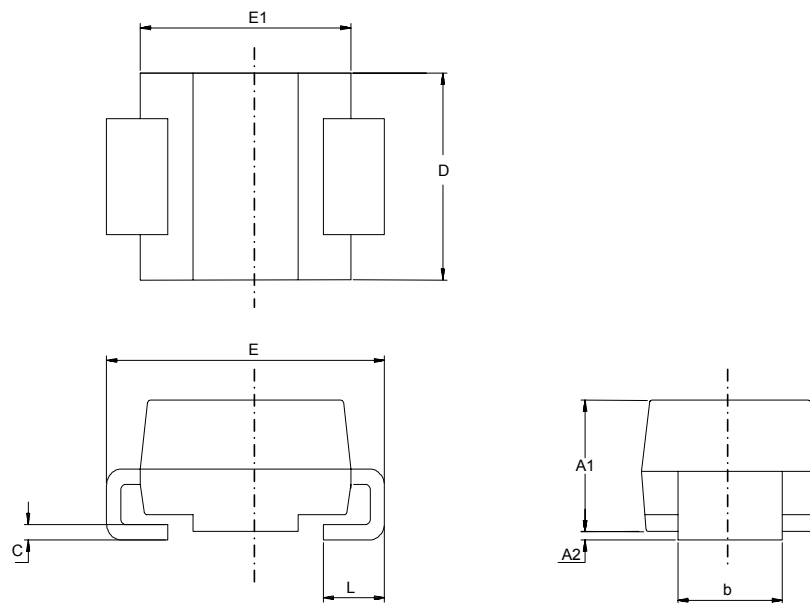
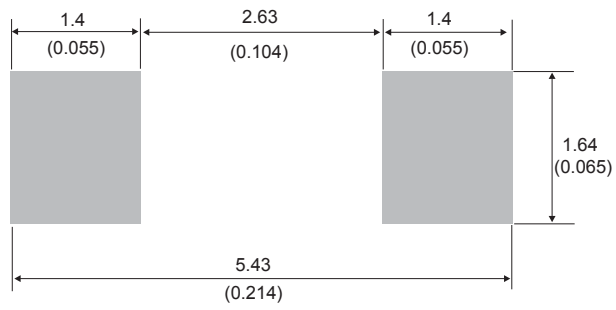


Table 4. SMA package mechanical data

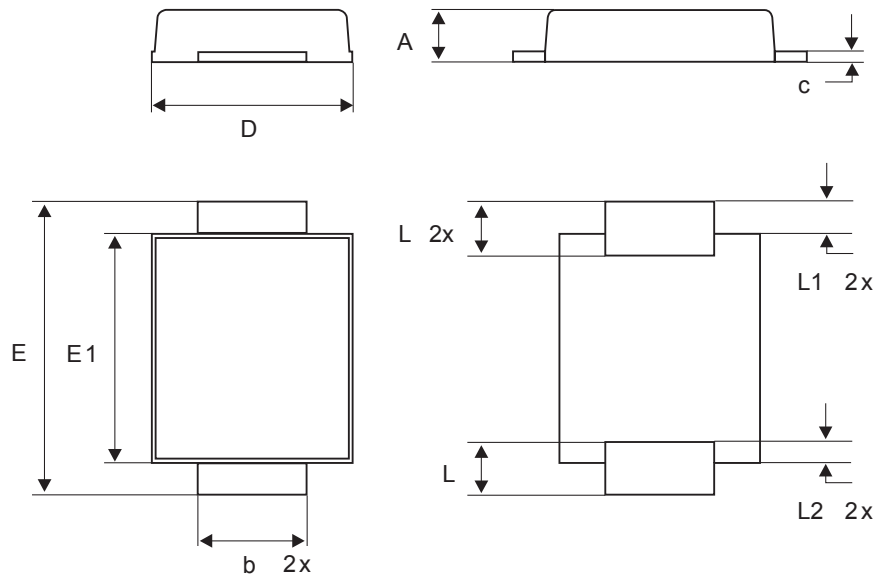
Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.074	0.097
A2	0.05	0.20	0.001	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.005	0.016
D	2.25	2.90	0.088	0.115
E	4.80	5.35	0.188	0.211
E1	3.95	4.60	0.155	0.182
L	0.75	1.50	0.029	0.060

Figure 17. SMA recommended footprint in mm (inches)



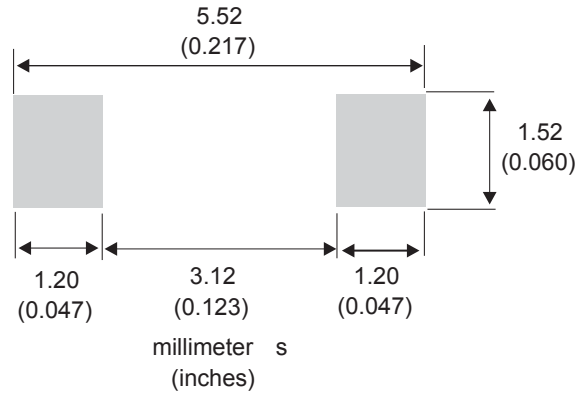
2.2 SMA Flat package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 18. SMA Flat package outline

Table 5. SMA Flat package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.044
b	1.25		1.65	0.049		0.065
c	0.15		0.40	0.005		0.016
D	2.25		2.95	0.088		0.117
E	4.80		5.60	0.188		0.221
E1	3.95		4.60	0.155		0.182
L	0.75		1.50	0.029		0.060
L1		0.50			0.020	
L2		0.50			0.020	

Figure 19. SMA Flat recommended footprint in mm (inches)



2.3 SMB Flat package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 20. SMB Flat package outline

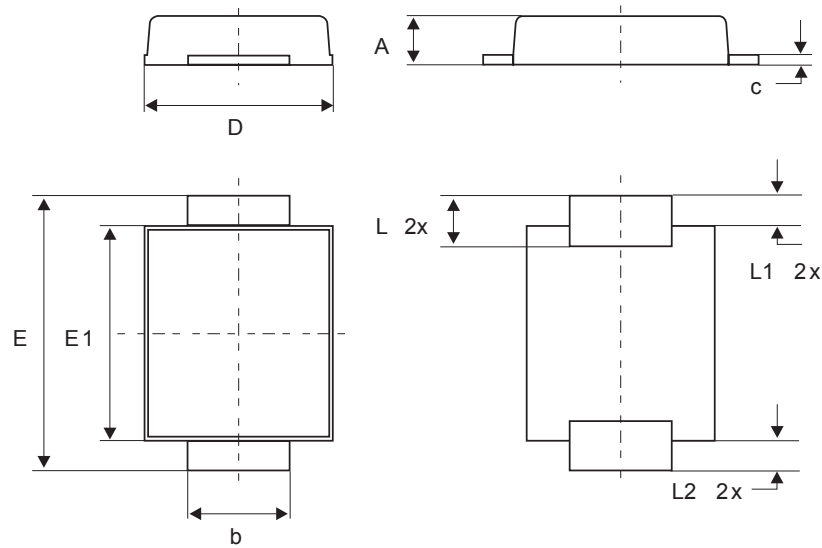
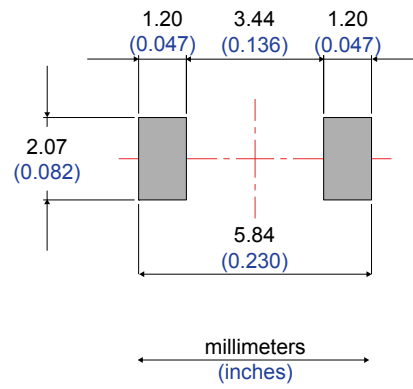


Table 6. SMB Flat mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.043
b	1.95		2.20	0.077		0.087
c	0.15		0.40	0.006		0.016
D	3.30		3.95	0.130		0.156
E	5.10		5.60	0.201		0.220
E1	4.05		4.60	0.159		0.181
L	0.75		1.50	0.030		0.059
L1		0.40			0.016	
L2		0.60			0.024	

Figure 21. Footprint recommendations, dimensions in mm (inches)



3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS2L30A	G30	SMA	0.068 g	5000	Tape and reel
STPS2L30UF	FG30	SMB Flat	0.050 g	5000	Tape and reel
STPS2L30AF	F30	SMA Flat	0.035 g	10000	Tape and reel

Revision history

Table 8. Document revision history

Date	Version	Changes
Jul-2003	3A	Last update.
Aug-2004	4	SMA package dimensions update. Reference A1 max. changed from 2.70mm (0.106inc.) to 2.03mm (0.080).
31-Jan-2007	5	Reformatted to current standard. Added ECOPACK statement. Added SMB flat package.
23-Apr-2008	6	Reformatted to current standards. Added SMA flat package.
30-Nov-2018	7	Updated Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified) and Figure 5. Normalized avalanche power derating versus pulse duration (T_j = 125 °C) .

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